PCN# : P5BKAA
Issue Date : Dec. 07, 2015

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples.

Implementation of change:

Expected First Shipment Date for Changed Product :Mar. 06, 2016

Expected First Date Code of Changed Product :1610

Description of Change (From) :
Front-end Wafer Fabrication site at Fairchild Salt Lake Utah, 6-inch wafers
Assembly and Test in Fairchild Semiconductor Penang, Malaysia and manufacturing source located in Thailand

Description of Change (To) :
Front-end Wafer Fabrication site at Fairchild Mt. Top, PA 8-inch wafers
Assembly and Test in Fairchild Semiconductor Cebu Philippines and manufacturing source located in Thailand
(Change already covered in PCN# P4A1AA distributed earlier)

Reason for Change:
Improve supply flexibility.
Better quality and yields through equipment and facility upgrades.
- Increased automation in handling and inspection in assembly.
Fairchild partners with foundries and assembly subcontractors.
- Best manufacturing practices, access to many customers methods and practices.
- Advanced technology for fast ramp of future new products and technologies.

Affected Product(s): Please refer to the list of affected products in the addendum attached in the PCN email you received. This list is based on an analysis of your companys procurement history.

Qualification Plan	Device	Package	Process	No. of Lots
Q20140001	FDMC6676BZ	MLDEUC08	ST3 PZ	3

Reliability Test	Condition	Standard	Device Name	FDMC6676BZ	FDMC6676BZ	FDMC6676BZ
			Lot No.	Q20140001AA	Q20140001AB	Q20140001AC
			Duration	Result/FA	Result/FA	Result/FA
Preconditioning	Per spec	JESD22A-113		0/158	0/158	0/158
HTGB	150C, Vgs=20V	JESD22-A108	1000hrs	0/79	0/79	0/79
HTRB	150C, Vr=80V	JESD22-A108	1000hrs	0/79	0/79	0/79
HTSL	175C	JESD22-A103	500hrs	0/79	0/79	0/79
HAST	130C, 85%RH, Vr=42V	JESD22-A110	96hrs	0/79	0/79	0/79
MSL		J-STD_020		0/22	0/22	0/22
PRCL	T On/Off=2.0min, Delta Tj=100C	Mil Std 750-1036	10000cyc	0/79	0/79	0/79
TMCL	-65C,150C	JESD22-A104	500cyc	0/79	0/79	0/79

Qualification Plan	Device	Package	Process	No. of Lots
Q20140002	FDS6681Z_G	NMSONC08	ST3 PZ	3

Reliability Test	Condition	Standard	Device Name	FDS6681Z_G	FDS6681Z_G	FDS6681Z_G
			Lot No.	Q20140002AA	Q20140002AB	Q20140002AC
			Duration	Result/FA	Result/FA	Result/FA
Preconditioning	Per spec	JESD22A-113		0/158	0/158	0/158
HTGB	150C, Vgs=20V	JESD22-A108	1000hrs	0/79	0/79	0/79
HTRB	150C, Vr=80V	JESD22-A108	1000hrs	0/79	0/79	0/79
HTSL	175C	JESD22-A103	500hrs	0/79	0/79	0/79
HAST	130C, 85%RH, Vr=42V	JESD22-A110	96hrs	0/79	0/79	0/79
MSL		J-STD_020		0/22	0/22	0/22
PRCL	T On/Off=2.0min, Delta Tj=100C	Mil Std 750-1036	10000cyc	0/79	0/79	0/79
TMCL	-65C,150C	JESD22-A104	500cyc	0/79	0/79	0/79